



# Product End-of-Life Disassembly Instructions

**Product Category: Notebooks**

**Marketing Name / Model**

**[List multiple models if applicable.]**

HP 255 G5 Notebook PC

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	1
Batteries	All types including standard alkaline and lithium coin or button style batteries	2
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	1
Cathode Ray Tubes (CRT)		
Capacitors / condensers (Containing PCB/PCT)		
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		
External electrical cables and cords	Power cords Adapters	2
Gas Discharge Lamps		
Plastics containing Brominated Flame Retardants		
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	
Components and waste containing asbestos		
Components, parts and materials containing refractory ceramic fibers		
Components, parts and materials containing radioactive substances		

## 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

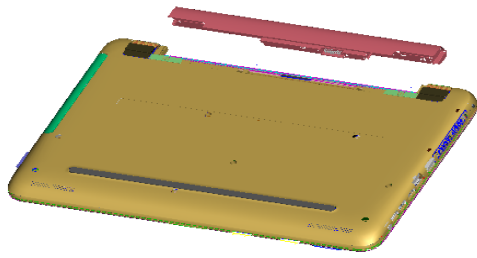
Tool Description	Tool Size (if applicable)
Screw Driver	No.0
Description #2	
Description #3	
Description #4	
Description #5	

## 3.0 Product Disassembly Process

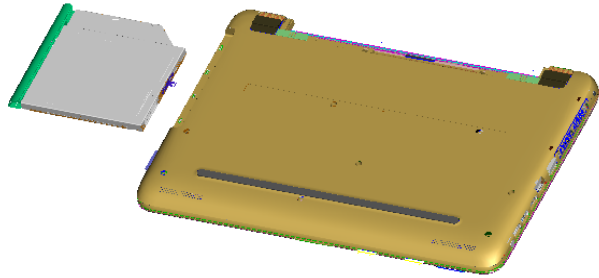
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove Battery
2. Remove ODD Module
3. Remove Logic Low
4. Remove HDD Module
5. Remove Speaker
6. Remove USB PCB
7. Remove Fan
8. Remove MB PCB
9. Remove TB PCB
10. Remove Logic up
11. Remove LCD Bezel
12. Remove Panel
13. Remove Hinge
14. Remove webcam
- 15.
- 16.
- 17.
- 18.
- 19.
- 20.

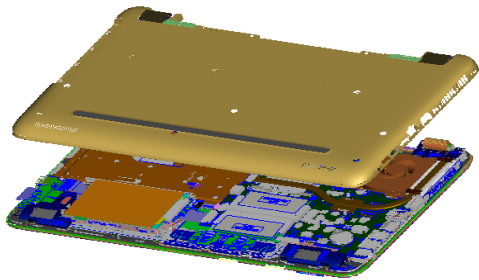
3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).



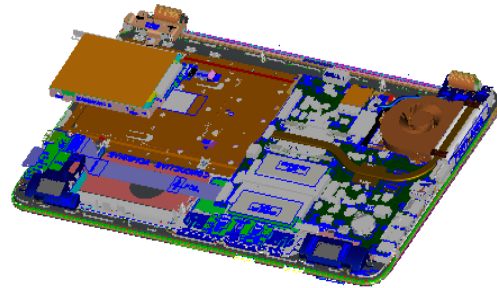
Step 1 Remove Battery



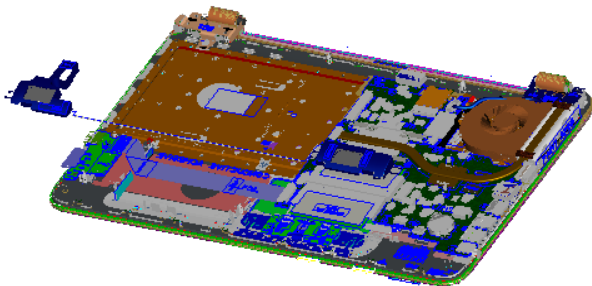
Step 2 Remove ODD Module



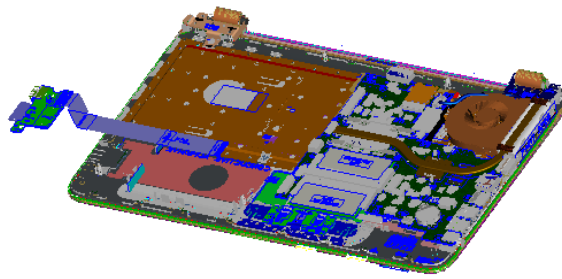
Step 3 Remove Logic Low



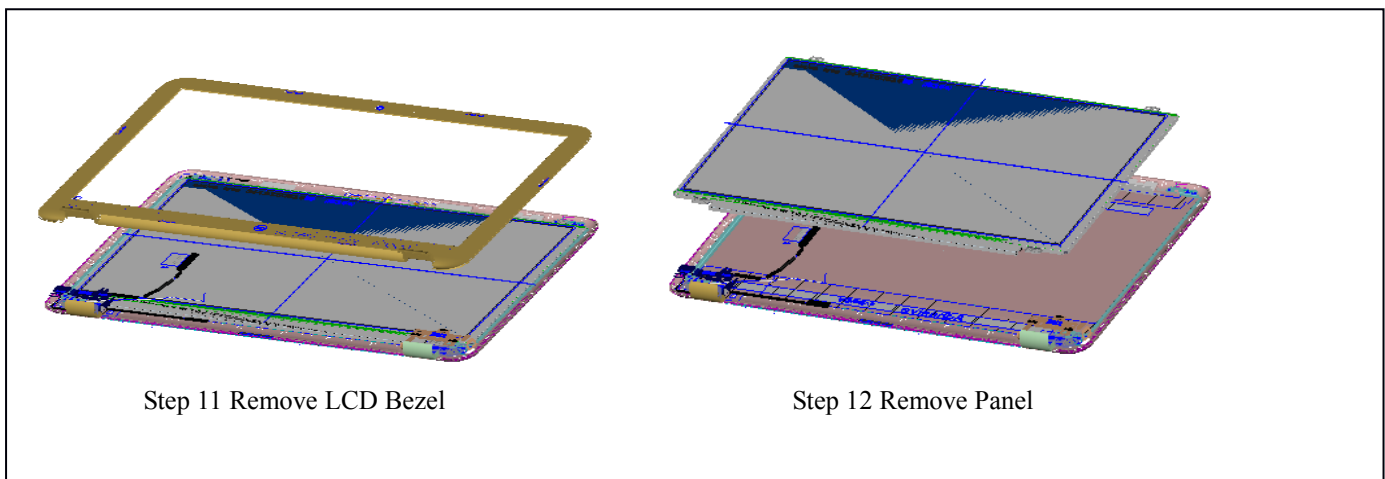
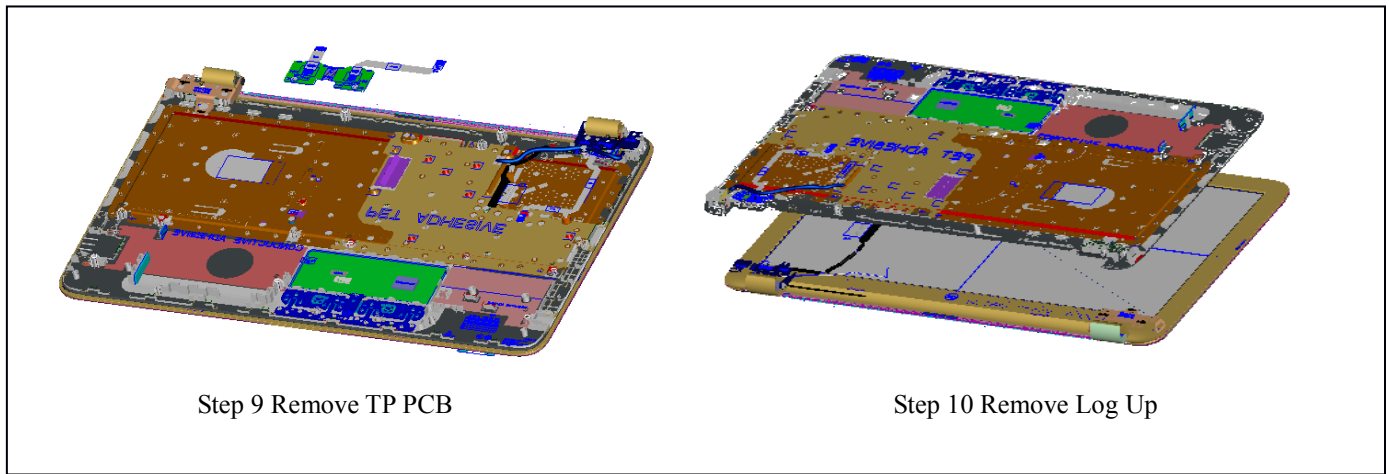
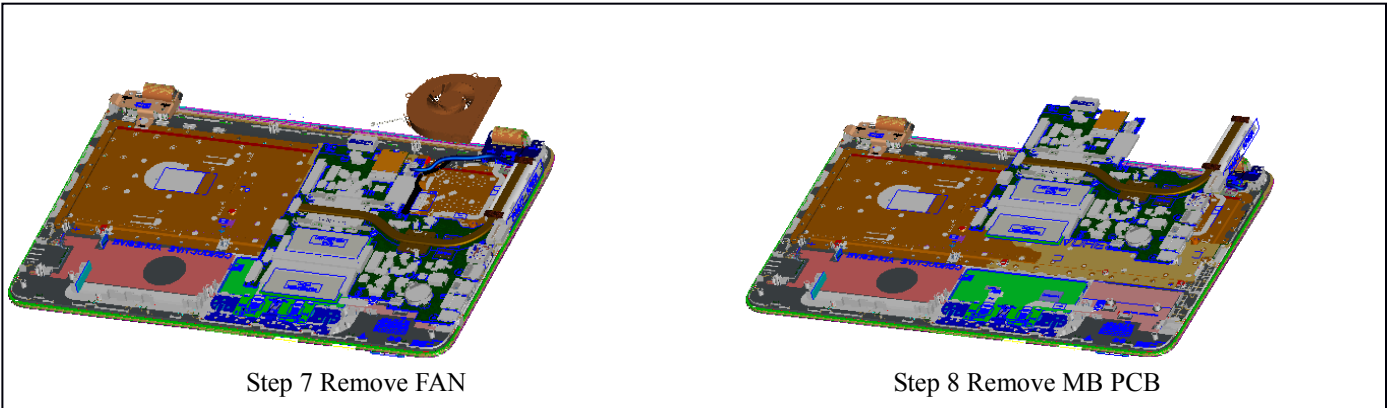
Step 4 Remove HDD module

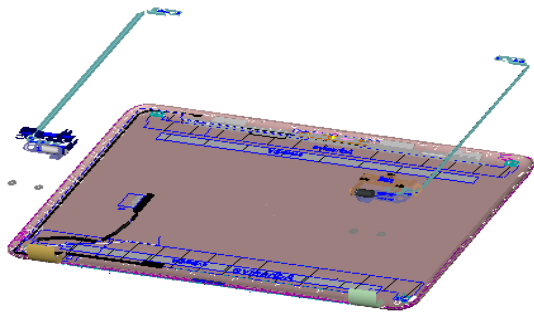


Step 5 Remove Speaker

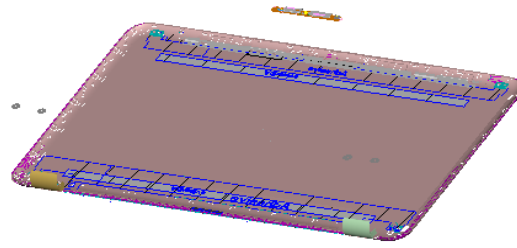


Step 6 Remove USB PCB





Step 13 Remove Hinge



Step 14 Remove Webcam